CPC1718
ISOPLUS™-264 DC Power Relay

Parameter	Rating	Units
Blocking Voltage	100	V_P
Load Current		
With 5°C/W Heat Sink	17.5	A_{DC}
No Heat Sink	6.75	
On-resistance	0.075	Ω
$R_{\theta JC}$	0.3	°C/W

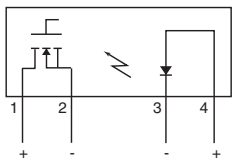
Features

- 100% Solid State
- Compact ISOPLUS-264 Power Package
- Low Thermal Resistance (0.3°C/W)
- 17.5A_{DC} Load Current with 5°C/W Heat Sink
- Electrically Non-conductive Thermal Pad for Heat Sink Applications
- Low Drive Power Requirements
- Arc-Free With No Snubbing Circuits
- 2500V_{rms} Input/Output Isolation
- No EMI/RFI Generation
- Machine Insertable, Wave Solderable

Applications

- Industrial Controls
- Motor Control
- Robotics
- Medical Equipment—Patient/Equipment Isolation
- Instrumentation
  - Multiplexers
  - Data Acquisition
  - Electronic Switching
  - I/O Subsystems
  - Meters (Watt-Hour, Water, Gas)
- Transportation Equipment
- Aerospace/Defense

Pin Configuration



Description

Clare and IXYS have combined to bring OptoMOS® technology, reliability and compact size to a new family of High Power Solid State Relays. As part of this new family, the CPC1718 single-pole, normally open (1-Form-A) DC Solid State Relay employs optically coupled MOSFET technology to provide 2500V_{rms} of input to output isolation.

The output is constructed with an efficient MOSFET switch and photovoltaic die that uses Clare's patented OptoMOS architecture while the input GaAlAs infrared LED provides the optically coupled control. The combination of low on-resistance and high load current handling capability makes this relay suitable for a variety of high performance DC switching applications.

The unique ISOPLUS-264 package pioneered by IXYS allows solid state relays to achieve the highest load current and power ratings. This package features an IXYS unique process where the silicon chips are soft soldered onto the Direct Copper Bond (DCB) substrate instead of the usual copper leadframe. The DCB ceramic, the same substrate used in high power modules, not only provides 2500V_{rms} isolation but also very low thermal resistance (0.3°C/W).

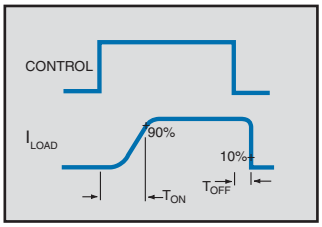
Approvals

- UL 508 Recognized Component: File # E69938

Ordering Information

Part Number	Description
CPC1718J	ISOPLUS-264 (25 per tube)

Switching Characteristics of Normally Open (Form A) Devices



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Absolute Maximum Ratings

Parameter	Ratings	Units
Blocking Voltage	100	V_P
Reverse Input Voltage	5	V
Input Control Current	100	mA
Peak (10ms)	1	A_{DC}
Input Power Dissipation	150	mW
Isolation voltage, Input to Output	2500	V_{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

Electrical absolute maximum ratings are at 25°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Electrical Characteristics

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics	**T_A=25°C**					
Load Current [1]						
Peak	t ≤ 10ms	I_L	-	-	40	A_P
Continuous	No Heat Sink				6.75	A_{DC}
Continuous	T_C=25ºC				32	
Continuous	T_C=99ºC	$I_{L(99)}$			8.5	
On-Resistance [2]	I_F=10mA, I_L=1A	R_{ON}	-	0.030	0.075	Ω
Off-State Leakage Current	V_L=100V_P	I_{LEAK}	-	-	1	µA
Switching Speeds						
Turn-On	I_F=20mA, V_L=10V	T_{ON}	-	7.5	20	ms
Turn-Off		T_{OFF}	-	0.19	5	
Output Capacitance	V=25V, f=1MHz	C_{OUT}	-	1600	-	pF
Input Characteristics	**T_A=25°C**					
Input Control Current [3]	I_L=1A	I_F	-	-	10	mA
Input Dropout Current	-	I_F	0.6	-	-	mA
Input Voltage Drop	I_F=5mA	V_F	0.9	1.2	1.4	V
Reverse Input Current	V_R=5V	I_R	-	-	10	µA
Common Characteristics	**T_A=25°C**					
Capacitance Input to Output	-	$C_{I/O}$	-	1	-	pF

[1] Higher load currents possible with proper heatsinking.
[2] Measurement taken within 1 second of on time.
[3] For applications requiring high temperature operation (greater than 60ºC) an LED drive current of 20mA is recommended.

Thermal Characteristics

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Thermal Resistance (junction to case)	-	$R_{\theta JC}$	-	-	0.3	°C/W
Thermal Resistance (junction to ambient)	Free air	$R_{\theta JA}$	-	33	-	°C/W
Junction Temperature (operation)	-	T_J	-40	-	100	°C

Thermal Management

Device high current characterization was performed using Kunze heat sink KU 1-159, phase change thermal interface material KU-ALC 5, and transistor clip KU 4-499/1. This combination provided an approximate junction-to-ambient thermal resistance of 12.5°C/W.

Heat Sink Calculation

Higher load currents are possible by using lower thermal resistance heat sink combinations.

Heat Sink Rating

$$R_{\theta CA} = \frac{(T_J - T_A)\, I_{L(99)}^{\,2}}{I_L^{\,2} \bullet P_{D(99)}} - R_{\theta JC}$$

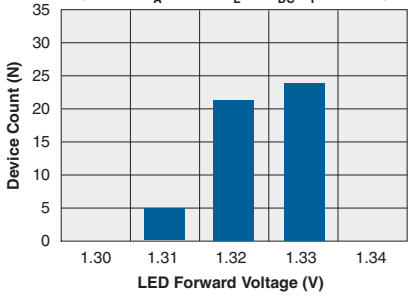
T_J = Junction Temperature (°C), $T_J \leq 100°C$ *
T_A = Ambient Temperature (°C)
$I_{L(99)}$ = Load Current with Case Temperature @ 99°C (A_{DC})
I_L = Desired Operating Load Current (A_{DC}), $I_L \leq I_{L(MAX)}$
$R_{\theta JC}$ = Thermal Resistance, Junction to Case (°C/W) = 0.3°C/W
$R_{\theta CA}$ = Thermal Resistance of Heat Sink & Thermal Interface Material , Case to Ambient (°C/W)
$P_{D(99)}$ = Maximum power dissipation with case temperature held at 99°C = 3.33W

* Elevated junction temperature reduces semiconductor lifetime.

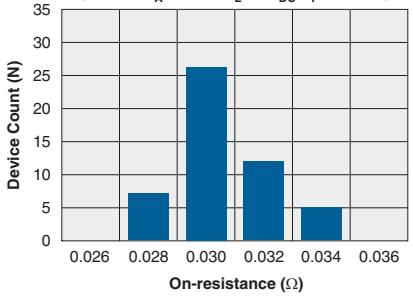
*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

PERFORMANCE DATA*

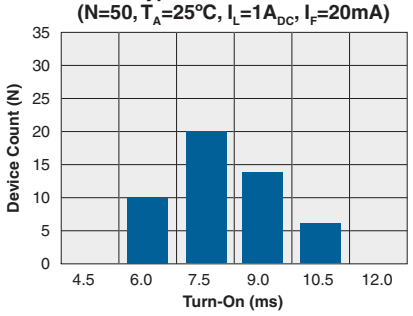
CPC1718
Typical LED Forward Voltage Drop
(N=50, T_A=25°C, I_L=1A_{DC}, I_F=10mA)



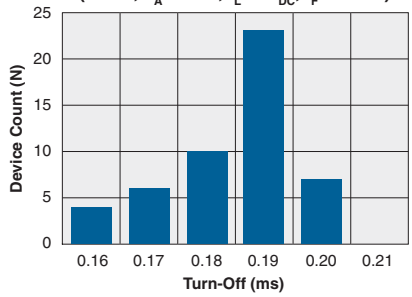
CPC1718
Typical On-Resistance Distribution
(N=50, T_A=25°C, I_L=1A_{DC}, I_F=10mA)



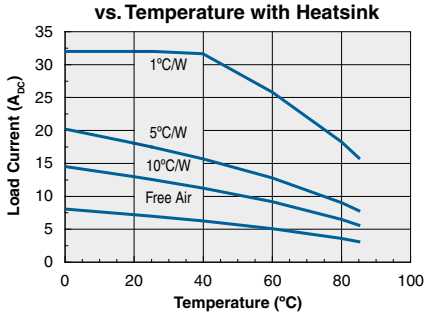
CPC1718
Typical Turn-On Time
(N=50, T_A=25°C, I_L=1A_{DC}, I_F=20mA)



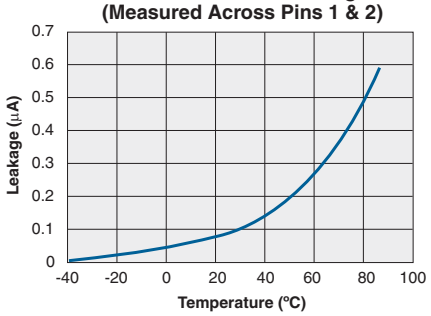
CPC1718
Typical Turn-Off Time
(N=50, T_A=25°C, I_L=1A_{DC}, I_F=20mA)



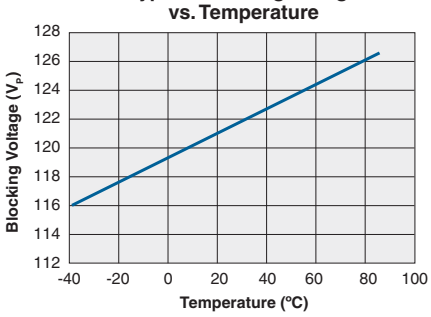
CPC1718
Maximum Load Current
vs. Temperature with Heatsink



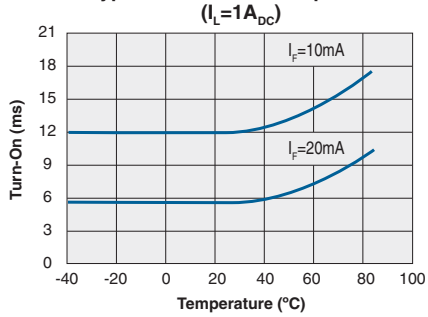
CPC1718
Typical Leakage vs. Temperature
at Maximum Rated Voltage
(Measured Across Pins 1 & 2)



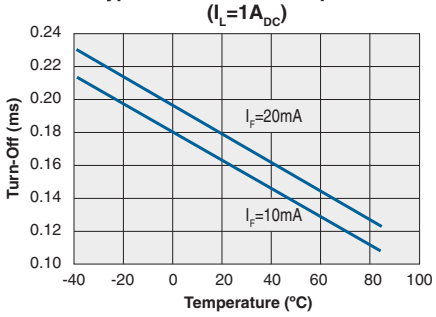
CPC1718
Typical Blocking Voltage
vs. Temperature



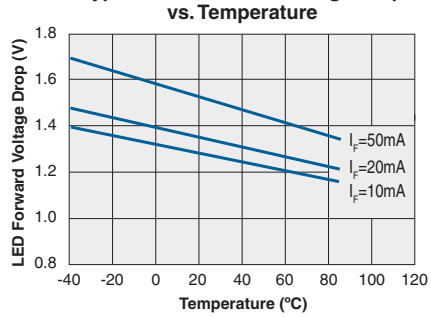
CPC1718
Typical Turn-On vs. Temperature
(I_L=1A_{DC})



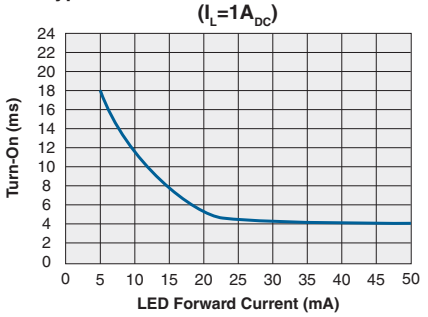
CPC1718
Typical Turn-Off vs. Temperature
(I_L=1A_{DC})



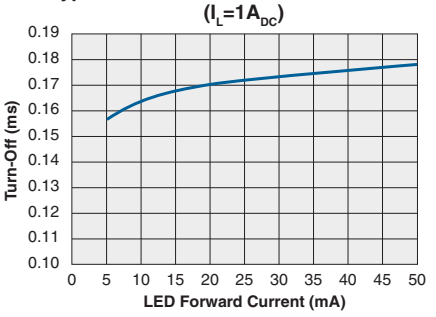
CPC1718
Typical LED Forward Voltage Drop
vs. Temperature



CPC1718
Typical Turn-On vs. LED Forward Current
(I_L=1A_{DC})



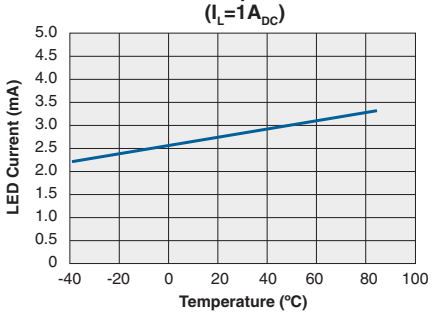
CPC1718
Typical Turn-Off vs. LED Forward Current
(I_L=1A_{DC})



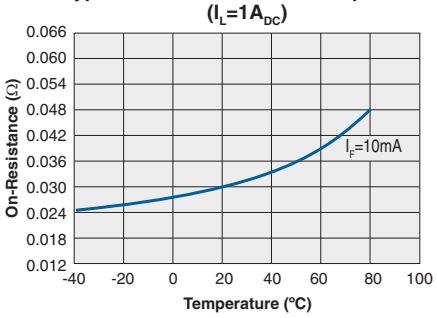
*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

PERFORMANCE DATA*

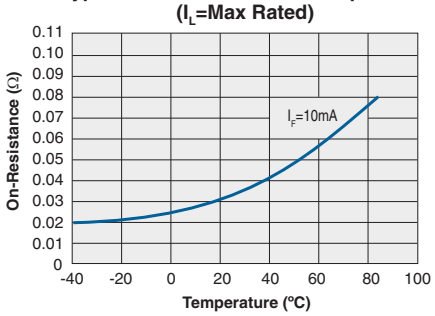
CPC1718
Typical I_F for Switch Operation vs. Temperature (I_L=1A_{DC})



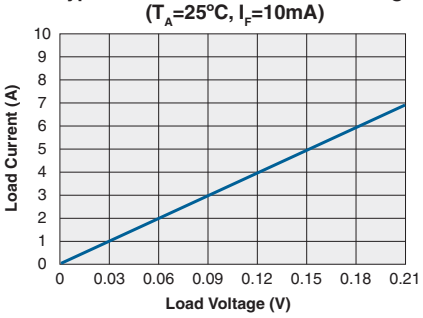
CPC1718
Typical On-Resistance vs. Temperature (I_L=1A_{DC})



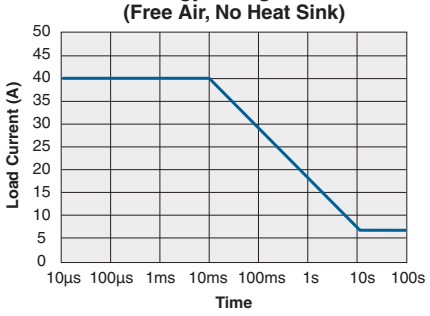
CPC1718
Typical On-Resistance vs. Temperature (I_L=Max Rated)



CPC1718
Typical Load Current vs. Load Voltage (T_A=25ºC, I_F=10mA)



CPC1718
Energy Rating Curve (Free Air, No Heat Sink)



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Manufacturing Information

Soldering

For proper assembly, the component must be processed in accordance with the current revision of IPC/JEDEC standard J-STD-020. Failure to follow the recommended guidelines may cause permanent damage to the device resulting in impaired performance and/or a reduced lifetime expectancy.

Washing

Clare does not recommend ultrasonic cleaning or the use of chlorinated solvents.

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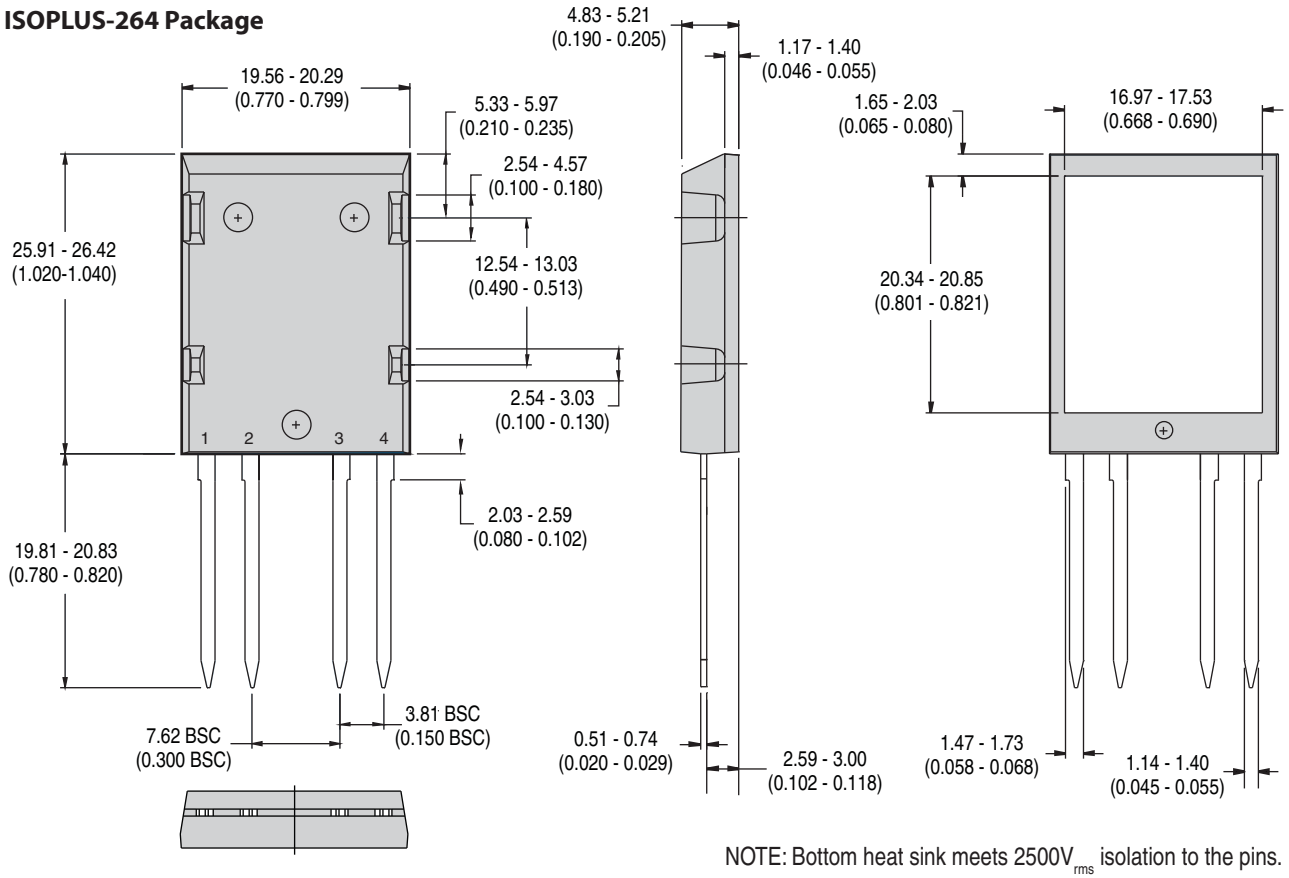
MECHANICAL DIMENSIONS:

ISOPLUS-264 Package



NOTE: Bottom heat sink meets 2500V_{rms} isolation to the pins.

DIMENSIONS
MIN - MAX mm
(MIN - MAX inches)

For additional information please visit our website at: www.clare.com

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